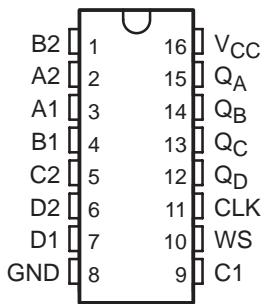


- Selects One of Two 4-Bit Data Sources and Synchronously Stores Data With System Clock
- Applications:
  - Dual Source for Operands and Constants in Arithmetic Processor; Can Release Processor Register Files for Acquiring New Data
  - Implements Separate Registers Capable of Parallel Exchange of Contents, Yet Retains External Load Capability
  - Has Universal-Type Register for Implementing Various Shift Patterns, Including Compound Left-Right Capability
- Package Options Include Plastic Small-Outline (D) Packages and Standard Plastic (N) 300-mil DIPs

D OR N PACKAGE  
(TOP VIEW)



### description

The SN74AS298A is a quadruple 2-input multiplexer with storage that provides essentially the equivalent functional capabilities of two separate MSI functions (SN74AS157 and 'AS175A) in a 16-pin package.

When the word-select (WS) input is low, word 1 (A1, B1, C1, D1) is applied to the flip-flops. A high input to WS causes the selection of word 2 (A2, B2, C2, D2). The selected word is clocked to the output terminals on the negative-going edge of the clock pulse.

The SN74AS298A is characterized for operation from 0°C to 70°C.

FUNCTION TABLE

INPUTS		OUTPUTS <sup>†</sup>			
WS	CLK	Q <sub>A</sub>	Q <sub>B</sub>	Q <sub>C</sub>	Q <sub>D</sub>
L	↓	a1	b1	c1	d1
H	↓	a2	b2	c2	d2
X	H	Q <sub>A0</sub>	Q <sub>B0</sub>	Q <sub>C0</sub>	Q <sub>D0</sub>

<sup>†</sup> a1, a2, etc. = the level of steady-state input at A1, A2, etc.

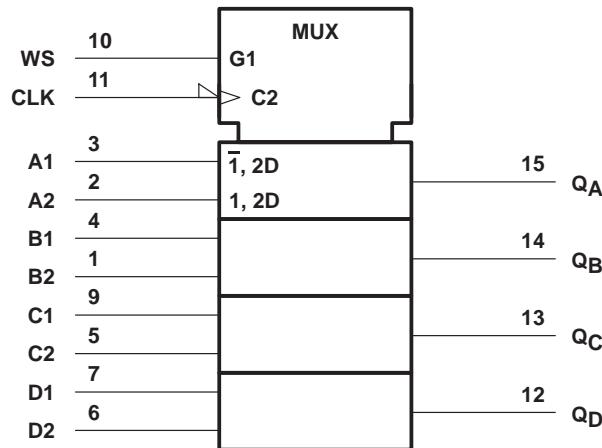
Q<sub>A0</sub>, Q<sub>B0</sub>, etc. = the level of Q<sub>A</sub>, Q<sub>B</sub>, etc. entered on the most recent ↓ transition of CLK

# **SN74AS298A**

## **QUADRUPLE 2-INPUT MULTIPLEXER WITH STORAGE**

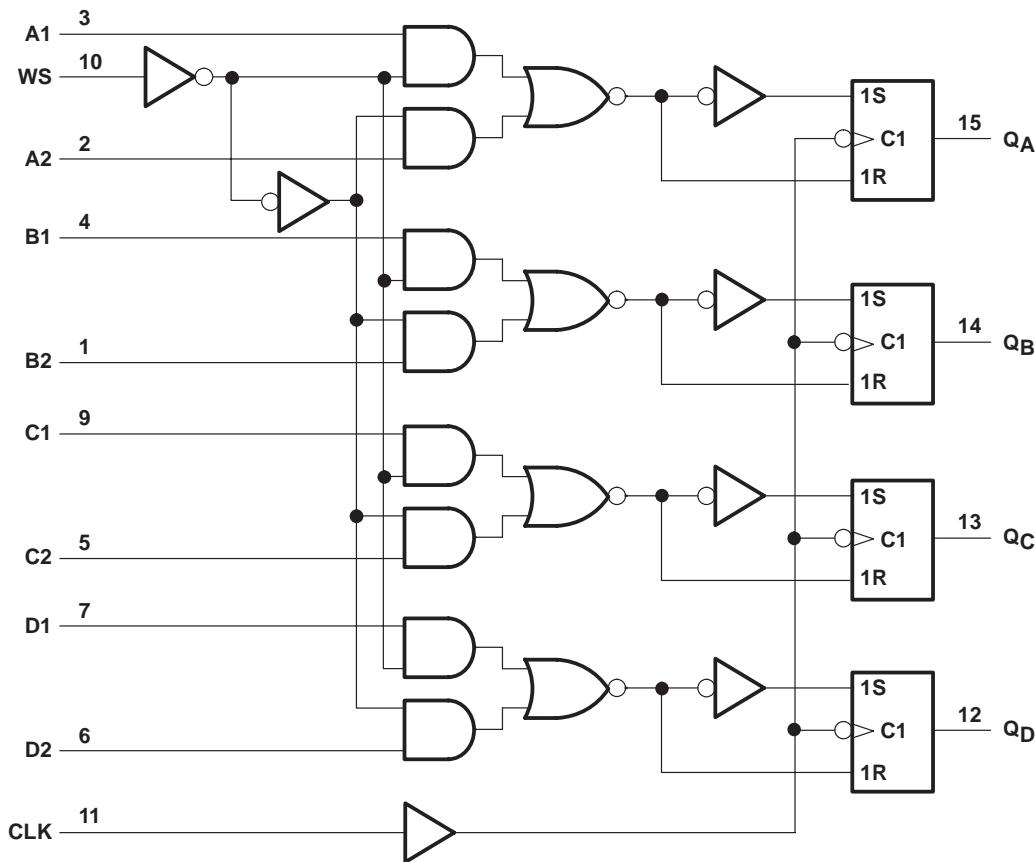
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## logic symbol†



<sup>†</sup>This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

## logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage, $V_{CC}$ .....	7 V
Input voltage, $V_I$ .....	7 V
Operating free-air temperature range, $T_A$ .....	0°C to 70°C
Storage temperature range .....	65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		MIN	NOM	MAX	UNIT
$V_{CC}$	Supply voltage	4.5	5	5.5	V
$V_{IH}$	High-level input voltage	2			V
$V_{IL}$	Low-level input voltage			0.8	V
$I_{OH}$	High-level output current			-2	mA
$I_{OL}$	Low-level output current			20	mA
$T_A$	Operating free-air temperature	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP <sup>‡</sup>	MAX	UNIT
$V_{IK}$	$V_{CC} = 4.5$ V, $I_I = -18$ mA			-1.2	V
$V_{OH}$	$V_{CC} = 4.5$ V to 5.5 V, $I_{OH} = -2$ mA	$V_{CC} - 2$			V
$V_{OL}$	$V_{CC} = 4.5$ V, $I_{OL} = 20$ mA	0.35	0.5		V
$I_I$	$V_{CC} = 5.5$ V, $V_I = 7$ V		0.1		mA
$I_{IH}$	WS		40		
	All others	$V_{CC} = 5.5$ V, $V_I = 2.7$ V	20		μA
$I_{IL}$	WS		-0.75		
	All others	$V_{CC} = 5.5$ V, $V_I = 0.4$ V	-0.5		mA
$I_O^§$	$V_{CC} = 5.5$ V, $V_O = 2.25$ V	-30	-112		mA
$I_{CCH}$	$V_{CC} = 5.5$ V		21	33	mA
$I_{CCL}$	$V_{CC} = 5.5$ V		22	36	mA

<sup>‡</sup> All typical values are at  $V_{CC} = 5$  V,  $T_A = 25^\circ\text{C}$ .

<sup>§</sup> The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current,  $I_{OS}$ .

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
$f_{clock}$	Clock frequency	0	62	MHz
$t_w$	Pulse duration, CLK high or low	8		ns
$t_{su}$	Setup time before CLK↓	Data	4.5	ns
		WS	13	
$t_h$	Hold time after CLK↓	Data	3.5	ns
		WS	1	

# SN74AS298A

## QUADRUPLE 2-INPUT MULTIPLEXER WITH STORAGE

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature,  $C_L = 50 \text{ pF}$  (unless otherwise noted) (see Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
$f_{\text{max}}$			62		MHz
$t_{\text{PLH}}$	CLK	Q	2	9	ns
$t_{\text{PHL}}$			1	11	

## APPLICATION INFORMATION

This versatile multiplexer can be connected to operate as a shift register that can shift  $n$  places in a single clock pulse.

Figure 1 illustrates a BCD shift register that shifts an entire 4-bit BCD digit in one clock pulse.

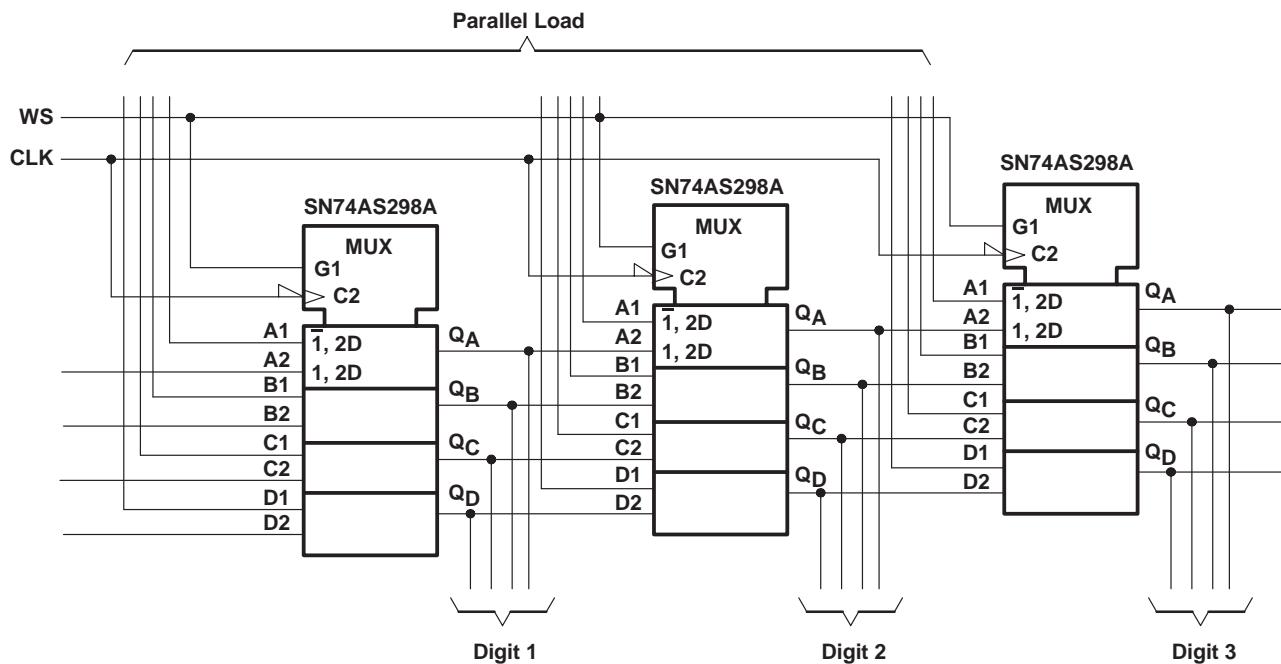


Figure 1. BCD Shift Register

When WS is high and the registers are clocked, the content of register 1 is transferred (shifted) to register 2, etc., effectively shifting the BCD digits one position. This application also retains a parallel-load capability, which means that new BCD data can be entered into the entire register with one clock pulse. This arrangement can be modified to perform the shifting of binary data for any number of bit locations.

Another function that can be implemented is a register designed specifically for supporting multiplier or division operations (see Figure 2).

When WS is low and the register is clocked, the outputs of the arithmetic/logic units (ALUs) are shifted one place. When WS is high and the registers are clocked, the data is shifted two places.

APPLICATION INFORMATION

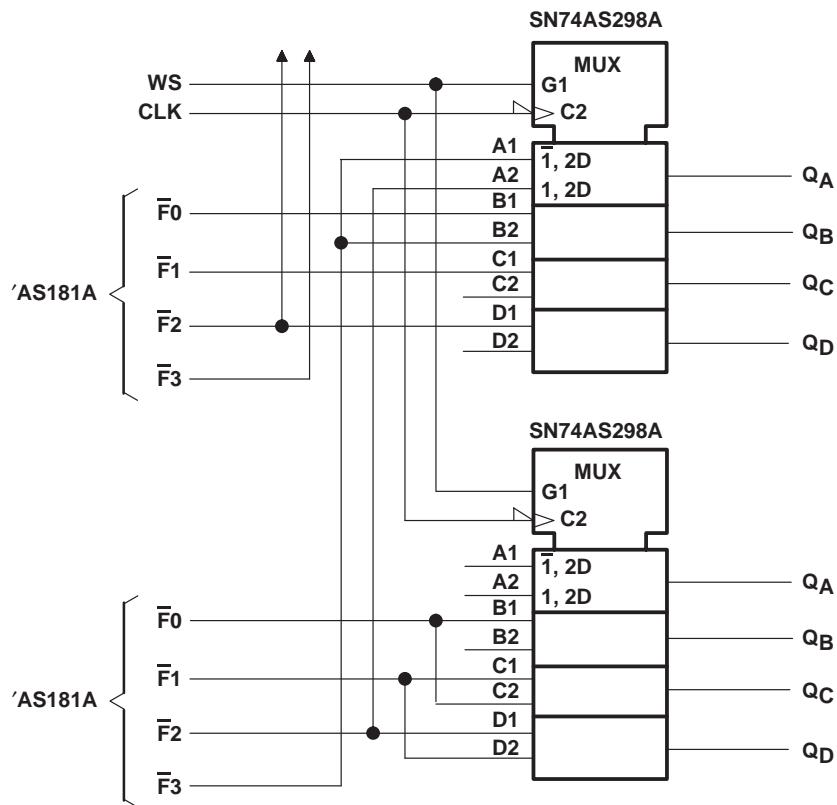


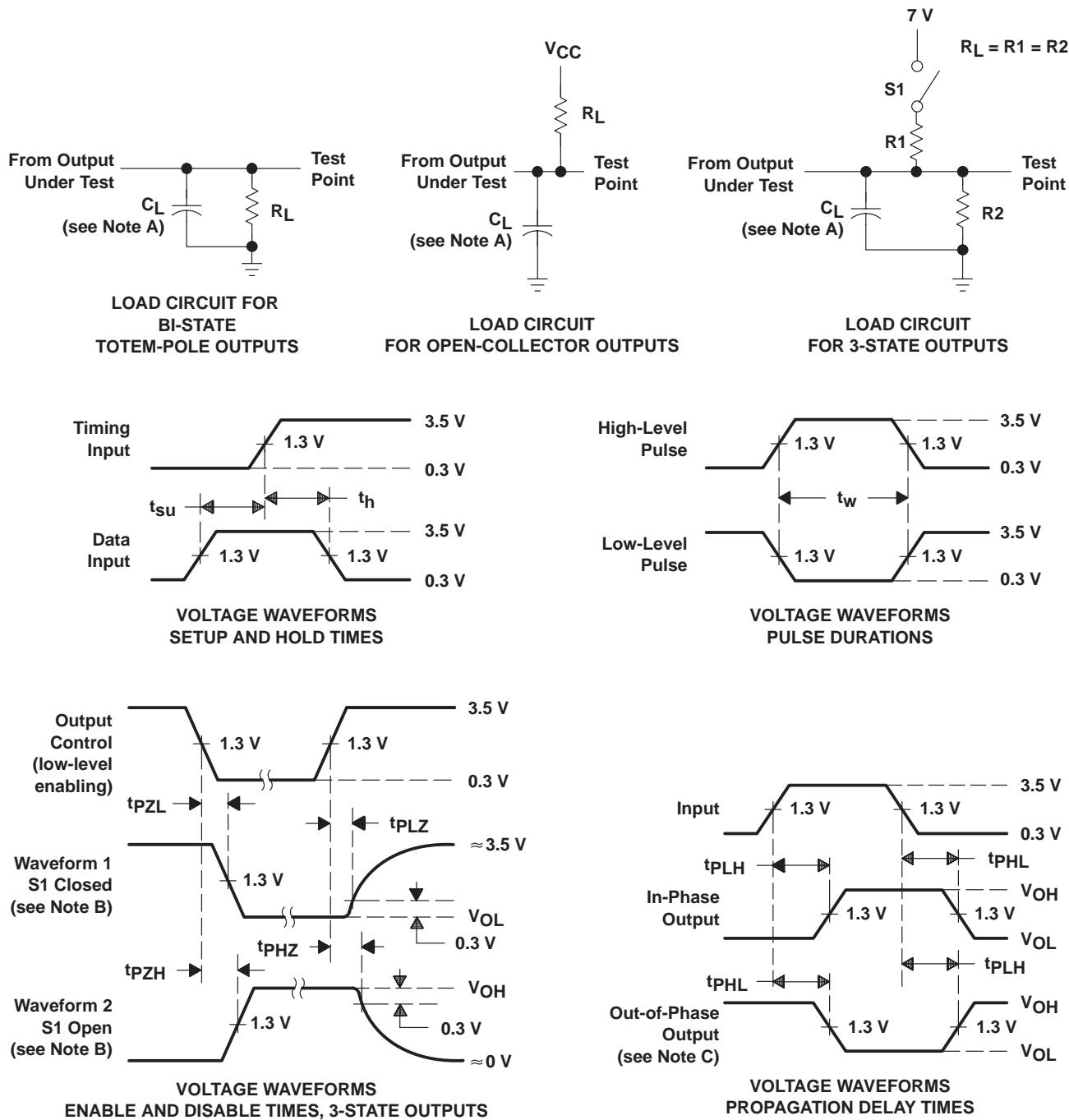
Figure 2. 1-Place/2-Place Shift Register

# SN74AS298A

## QUADRUPLE 2-INPUT MULTIPLEXER WITH STORAGE

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### PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.  
 D. All input pulses have the following characteristics:  $PRR \leq 1 \text{ MHz}$ ,  $t_r = t_f = 2 \text{ ns}$ , duty cycle = 50%.  
 E. The outputs are measured one at a time with one transition per measurement.

Figure 3. Load Circuits and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AS298AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS298A	<b>Samples</b>
SN74AS298AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS298AN	<b>Samples</b>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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## PACKAGE OPTION ADDENDUM

10-Jun-2014

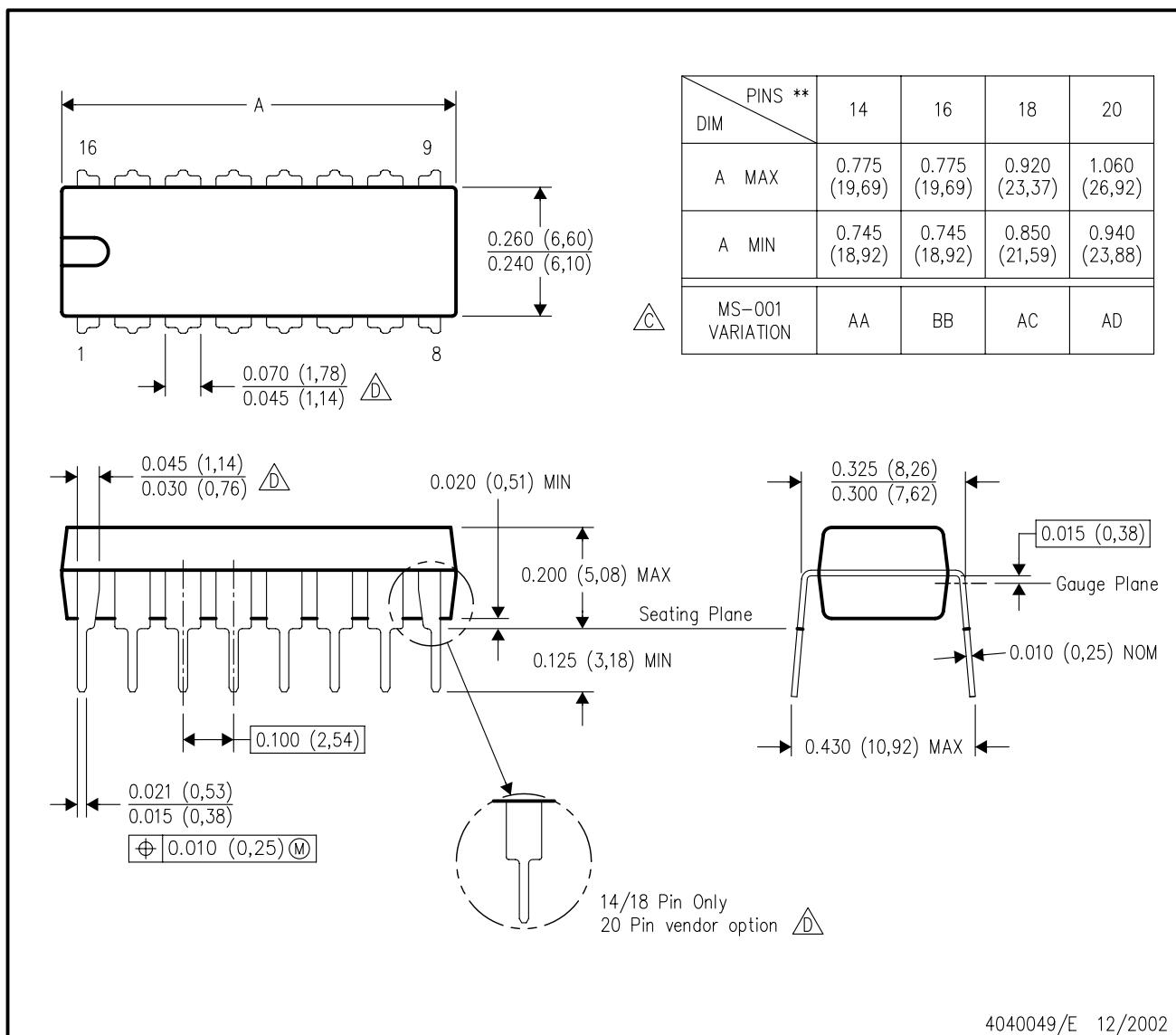
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## N (R-PDIP-T\*\*)

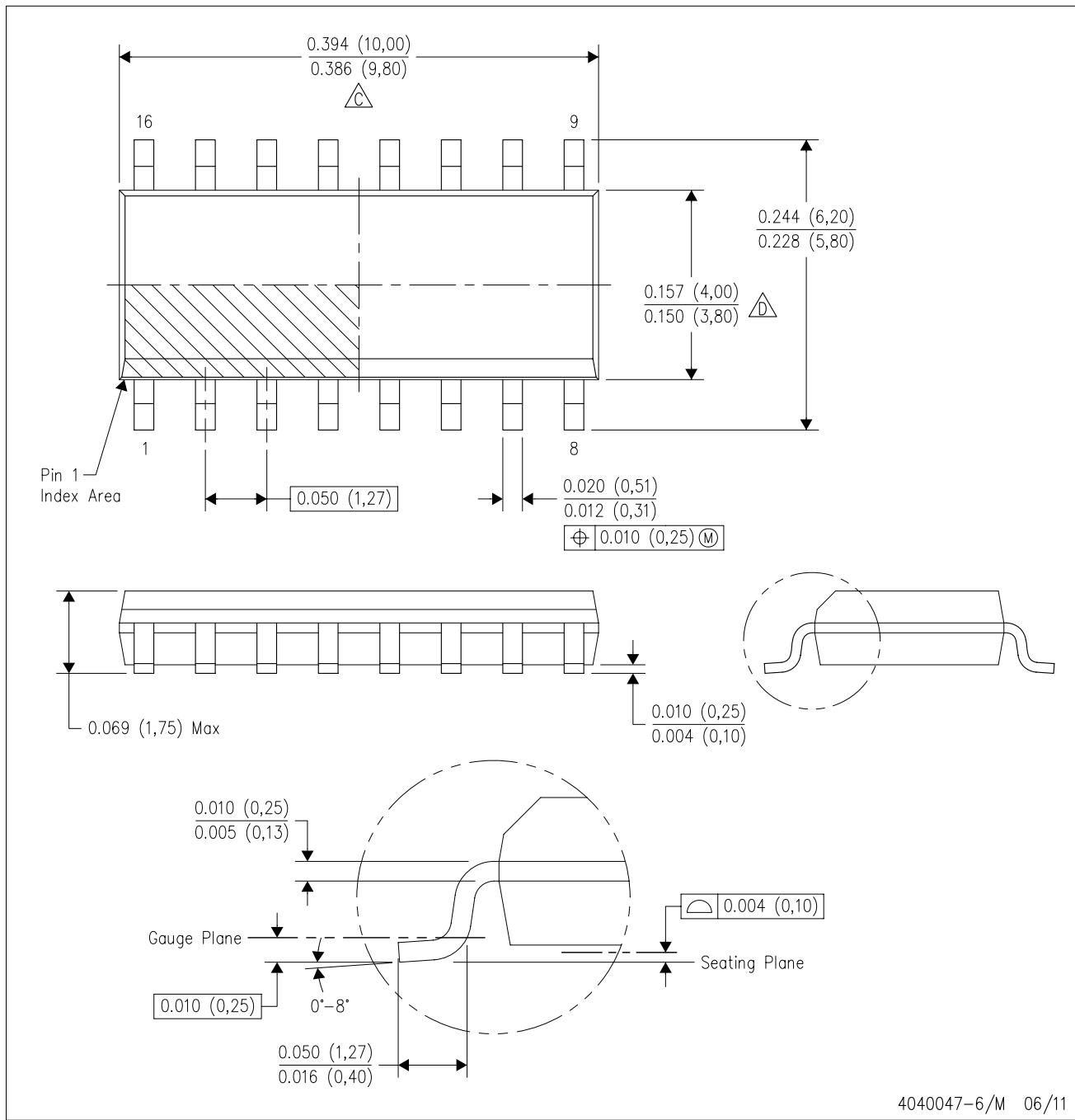
16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

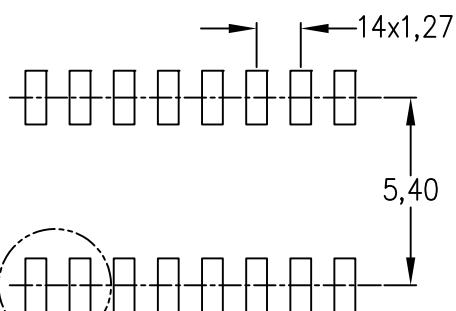
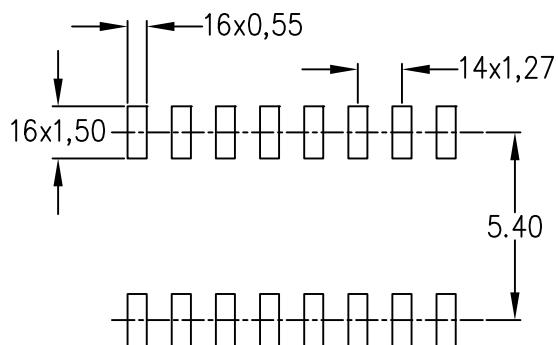
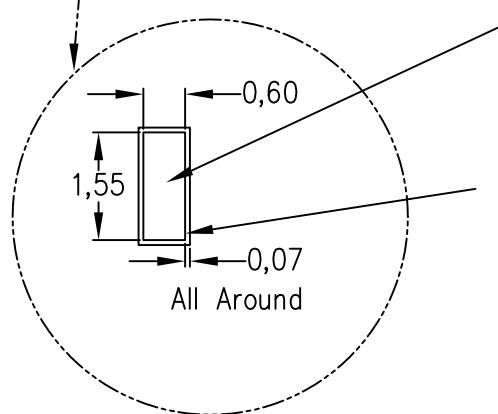
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.

D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.

E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE

Example Board Layout  
(Note C)Stencil Openings  
(Note D)Example  
Non Soldermask Defined PadExample  
Pad Geometry  
(See Note C)Example  
Solder Mask Opening  
(See Note E)

4211283-4/E 08/12

NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Publication IPC-7351 is recommended for alternate designs.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
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Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
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